



Pad Coordinates in Microns

1	0; 0	23	3307.5; 3983
2	0; 283	24	3576.5; 2830
3	0; 566	25	3576.5; 2547
4	0; 849	26	3576.5; 2264
5	0; 1132	27	3576.5; 1981
6	0; 1415	28	3576.5; 1698
7	0; 1698	29	3576.5; 1415
8	0; 1981	30	3576.5; 1132
9	0; 2264	31	3576.5; 849
10	0; 2547	32	3576.5; 566
11	0; 2830	33	3576.5; 283
12	194.5; 3983	34	3576.5; 0
13	477.5; 3983	35	3282.5; -204
14	760.5; 3983	36	2544; -127
15	1043.5; 3983	37	2354; -127
16	1326.5; 3983	38	2104.5; -83.5
17	1609.5; 3983	39	1914.5; -111
18	1892.5; 3983	40	1729; -111
19	2175.5; 3983	41	1424.5; -166.5
20	2458.5; 3983	42	1249.5; -166.5
21	2741.5; 3983	43	1074.5; -166.5
22	3024.5; 3983		

Note:
Pad designation for DIR = H/L
Example: for DIR = H, Pad 1 is HV_{OUT1}
for DIR = L, Pad 1 is HV_{OUT34}

HV7022-C

Pad	Function	Pad	Function	Pad	Function	Pad	Function	Pad	Function	Pad	Function
1	HV _{OUT1} /34	8	HV _{OUT8} /27	15	HV _{OUT15} /20	22	HV _{OUT22} /13	29	HV _{OUT29} /6	36	Data In
2	HV _{OUT2} /33	9	HV _{OUT9} /26	16	HV _{OUT16} /19	23	HV _{OUT23} /12	30	HV _{OUT30} /5	37	POL
3	HV _{OUT3} /32	10	HV _{OUT10} /25	17	HV _{OUT17} /18	24	HV _{OUT24} /11	31	HV _{OUT31} /4	38	V _{DD}
4	HV _{OUT4} /31	11	HV _{OUT11} /24	18	HV _{OUT18} /17	25	HV _{OUT25} /10	32	HV _{OUT32} /3	39	DIR
5	HV _{OUT5} /30	12	HV _{OUT12} /23	19	HV _{OUT19} /16	26	HV _{OUT26} /9	33	HV _{OUT33} /2	40	GND
6	HV _{OUT6} /29	13	HV _{OUT13} /22	20	HV _{OUT20} /15	27	HV _{OUT27} /8	34	HV _{OUT34} /1	41	CLK
7	HV _{OUT7} /28	14	HV _{OUT14} /21	21	HV _{OUT21} /14	28	HV _{OUT28} /7	35	V _{PP}	42	OE
										43	Data Out

Die Specifications

	mils		mm			
Die Size:	154.73	x 185.04	3.930	x 4.700	Back Side Metal:	None
Die Thickness:	20 ±1		0.50 ±0.02		Back Side Potential:	V _{PP}
Bond Pad Size:	4	x 4	0.10	x 0.10	Die Attach Material:	Ablestick 84-1 or equal
Bond Wire Size:	1.3		0.03		Bond Pad Metal:	Al/Si/Cu